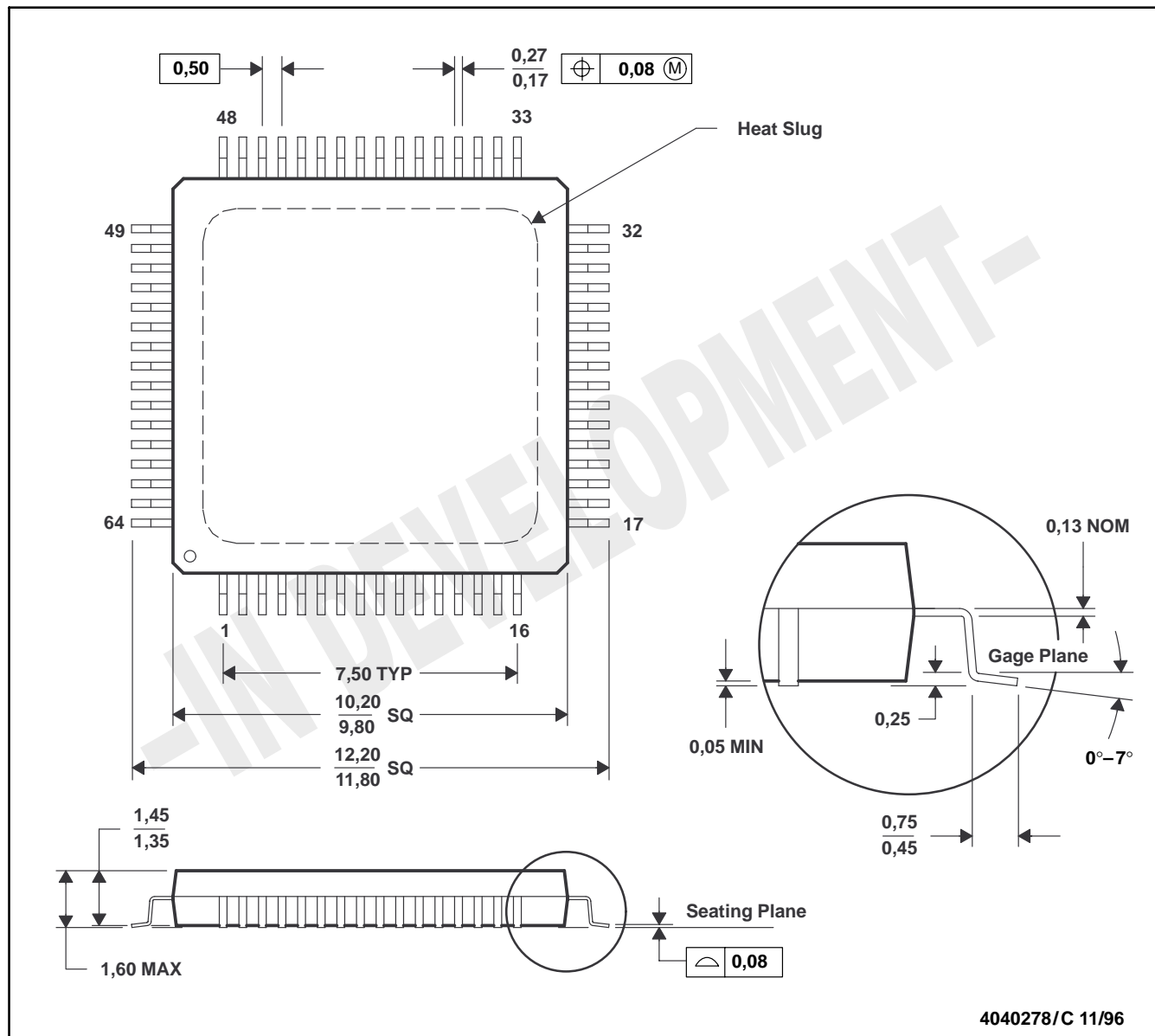


## PAJ (S-PQFP-G64)

## PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Thermally enhanced plastic package with a heat slug (HSL) exposed on package bottom
  - D. Falls within JEDEC MS-026

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